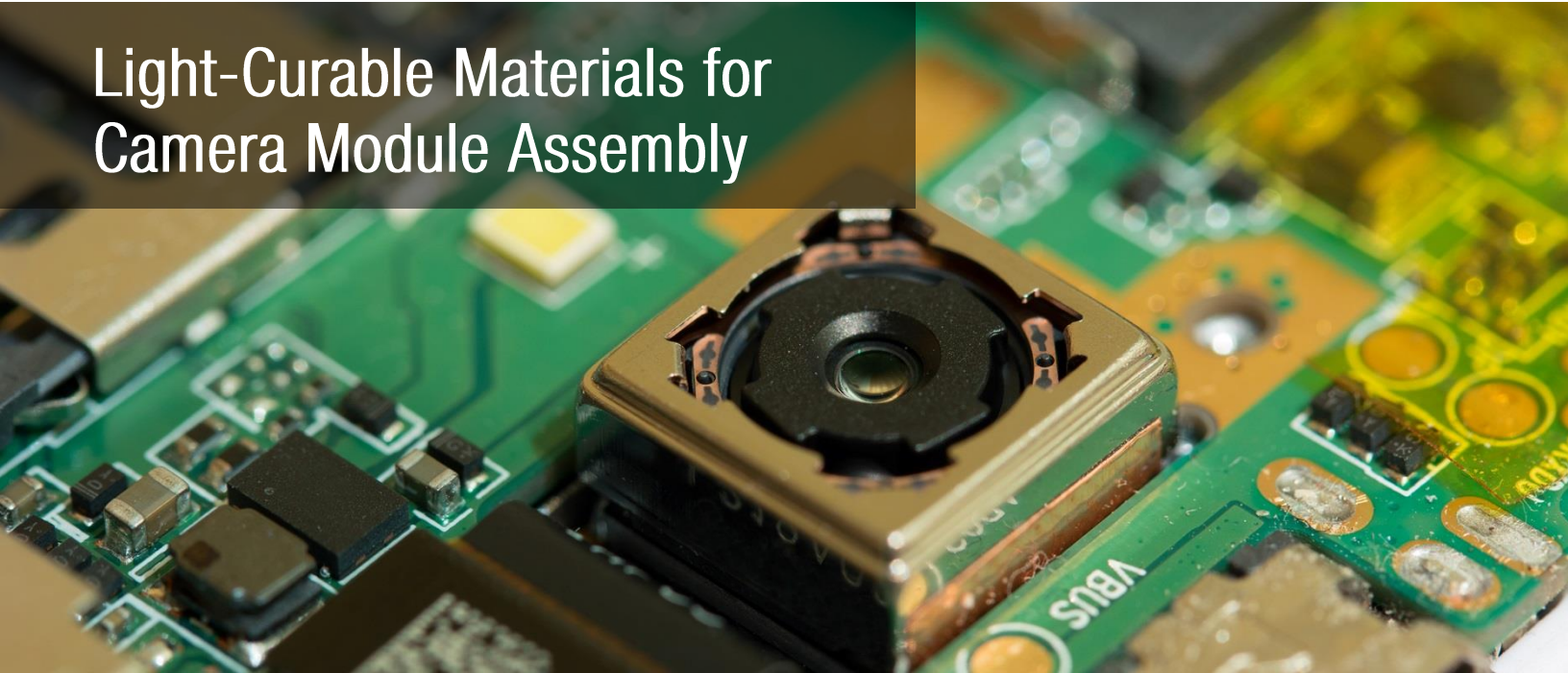


Light-Curable Materials for Camera Module Assembly



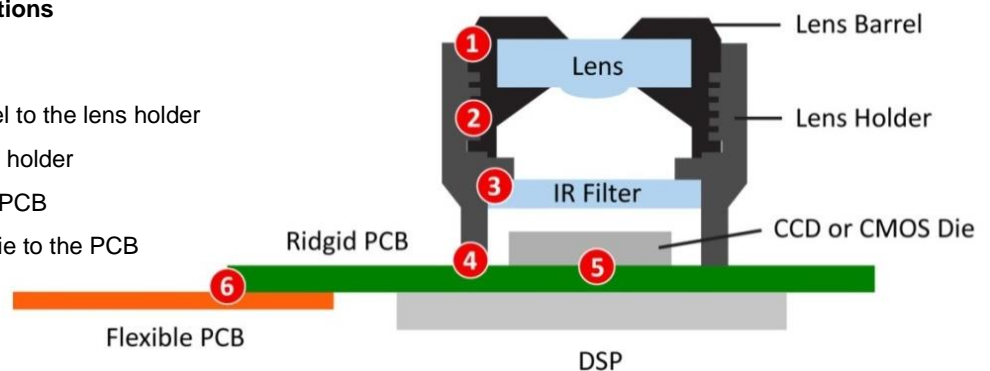
Faster, Stronger Bonds for Camera Module Assembly

Dymax light-curable adhesives are ideal for use in the assembly of camera modules used in smart connected devices, automobiles, and industrial camera systems. Our adhesives cure in seconds, providing greater product yields in a much shorter assembly time. They provide excellent adhesion to substrates typically used in the manufacture of electronic device housings and camera modules, and can withstand harsh conditions like the moisture and shock which electronic devices are often exposed to.

- Excellent adhesion to commonly used substrates in camera module assemblies
- Materials cure in seconds allowing faster processing and higher throughput
- Materials available for a variety of applications including active alignment, barrel fixturing, and FPC reinforcement
- Good resistance to moisture and shock

Typical Camera Module Applications

- 1 - Bonding the camera lens
- 2 - Fixturing the camera lens barrel to the lens holder
- 3 - Bonding the IR filter to the lens holder
- 4 - Bonding the lens holder to the PCB
- 5 - Attaching the CCD or CMOS die to the PCB
- 6 - Reinforcing the FPC



Product	UV/Visible Light	Moisture	Heat	Description	Substrates	Viscosity, cP/ mPas	Tensile at Break, MPa [psi]	Modulus of Elasticity, MPa [psi]
Flexible Printed Circuit (FPC) Reinforcement Typical requirements: Flexibility; Bend resistance								
9008	●			Remains flexible to -40°C; moisture resistant	Kapton®, DAP, Glass, Epoxy Board, Metal	4,500	10 [1,500]	45 [6,500]
9101	●	●		Flexible; moisture and thermal resistant	FR4, Kapton®, Glass	7,000	5.06 [735]	17.5 [2,550]
Active Alignment (Holder to FPC Bonding) Typical requirements: Low shrinkage; Low outgassing; Fast curing; Good adhesion to LCP								
9900-AA	●		●	Moisture and thermal resistant; flexible	LCP, PCB, FPC, Ceramic	43,492	57.7 [8,373]	1,962 [284,578]
Barrel Fixturing Typical requirements: Good surface dry								
3094-T-TF*	●			Fast curing; low shrinkage and stress	PA, PC, PMMA, PS	6,500	13.8 [2,000]	650 [94,317]
Fixturing Lens to Barrel Typical requirements: High Ti value; Good adhesion to PC and lens								
3094-GEL-REV-A	●			Fast curing; low shrinkage and stress	LCP, PC, PU, PS	30,000	12.4 [1,800]	179 [26,000]
3-20686**	●			Low outgassing; good adhesion to PC	PC, Metalized Plastics	4,000	48 [6,900]	760 [110,000]
9951-LR	●			Low reflection; easy to dispense; room temperature storage	PC, ABS, LCP, PA	15,000	48 [6,900]	760 [110,000]
Other Applications								
3094-T-REV-A	●			Fast curing; low shrinkage and stress	LCP, PC, PU, PS	11,750	14 [2,000]	698 [101,300]
6-621-GEL	●		●	Hard and clear bonds	Metals, Glass, PA, Ceramic,	25,000	28 [4,000]	730 [106,000]
9001-E-V3.0	●		●	Low ionic. Good electrical properties.	PC, Flex Circuit	400	750 [108,700]	17.2 [2,500]
9309-SC	●			Adhesion to various PCB substrates; formulated with See-Cure color-change technology	Leadframe, Ceramic, PCB, Silicon	45,000	22 [3,200]	163 [23,800]

*This product is not available for sale in Europe.

** This product is not available for sale in Asia.



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